

## N-Channel 20-V (D-S) MOSFET

### Key Features:

- Low  $r_{DS(on)}$  trench technology
- Low thermal impedance
- Fast switching speed

### Typical Applications:

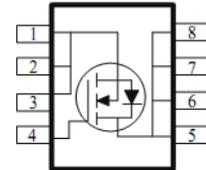
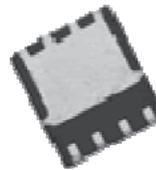
- DC/DC Conversion
- Power Routing
- Motor Drives

PRODUCT SUMMARY		
$V_{DS}$ (V)	$r_{DS(on)}$ (m $\Omega$ )	$I_D$ (A)
20	4 @ $V_{GS} = 4.5V$	23
	5 @ $V_{GS} = 2.5V$	19



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

DFN3x3-8L



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)				
Parameter		Symbol	Limit	Units
Drain-Source Voltage		$V_{DS}$	20	V
Gate-Source Voltage		$V_{GS}$	$\pm 8$	
Continuous Drain Current <sup>a</sup>	$T_A = 25^\circ\text{C}$	$I_D$	23.0	A
	$T_A = 70^\circ\text{C}$		16.9	
Pulsed Drain Current <sup>b</sup>		$I_{DM}$	100	
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	5.5	A
Power Dissipation <sup>a</sup>	$T_A = 25^\circ\text{C}$	$P_D$	3.5	W
	$T_A = 70^\circ\text{C}$		2	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Maximum	Units
Maximum Junction-to-Ambient <sup>a</sup>	$t \leq 10$ sec	$R_{\theta JA}$	35	$^\circ\text{C}/\text{W}$
	Steady State		81	

### Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

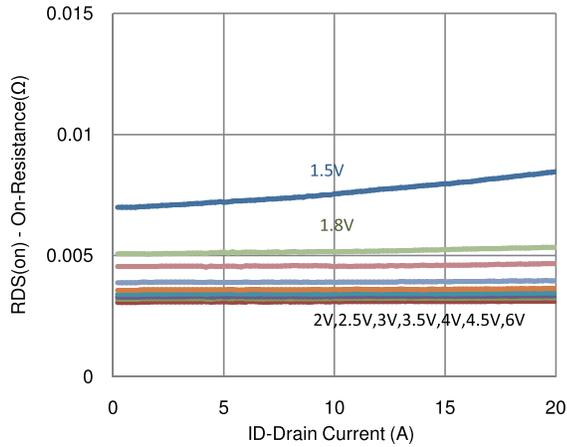
## Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static</b>						
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.4			V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 16 V, V_{GS} = 0 V$			1	$\mu A$
		$V_{DS} = 16 V, V_{GS} = 0 V, T_J = 55^\circ C$			25	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} = 5 V, V_{GS} = 4.5 V$	30			A
Drain-Source On-Resistance <sup>a</sup>	$r_{DS(on)}$	$V_{GS} = 4.5 V, I_D = 17.8 A$			4	m $\Omega$
		$V_{GS} = 2.5 V, I_D = 14.3 A$			5	
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = 10 V, I_D = 17.8 A$		18		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = 2.75 A, V_{GS} = 0 V$		0.64		V
<b>Dynamic <sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = 10 V, V_{GS} = 4.5 V,$ $I_D = 17.8 A$		71		nC
Gate-Source Charge	$Q_{gs}$			7.5		
Gate-Drain Charge	$Q_{gd}$			15		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = 10 V, R_L = 0.6 \Omega,$ $I_D = 17.8 A,$ $V_{GEN} = 4.5 V, R_{GEN} = 6 \Omega$		22		ns
Rise Time	$t_r$			43		
Turn-Off Delay Time	$t_{d(off)}$			300		
Fall Time	$t_f$			94		
Input Capacitance	$C_{iss}$	$V_{DS} = 15 V, V_{GS} = 0 V, f = 1 Mhz$		8742		pF
Output Capacitance	$C_{oss}$			511		
Reverse Transfer Capacitance	$C_{rss}$			498		

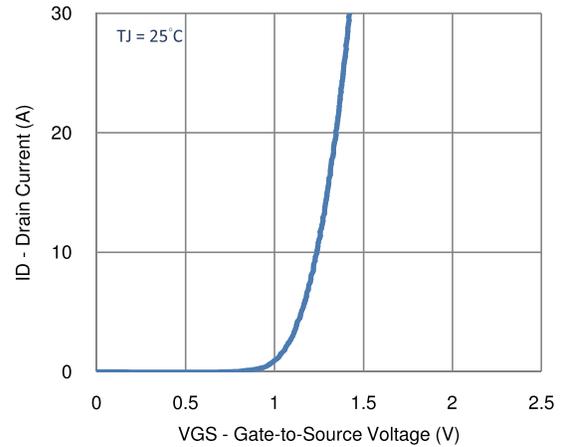
## Notes

- a. Pulse test: PW  $\leq$  300us duty cycle  $\leq$  2%.
- b. Guaranteed by design, not subject to production testing.

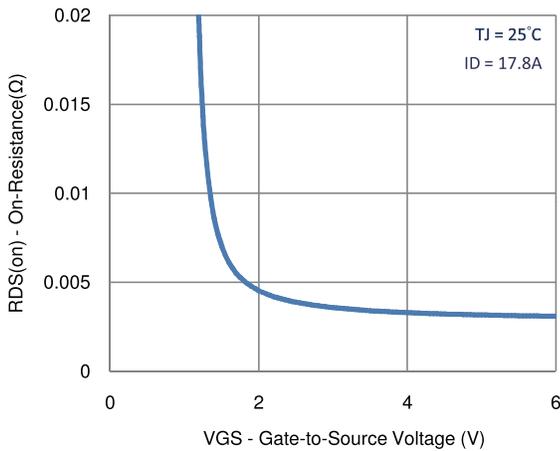
## Typical Electrical Characteristics



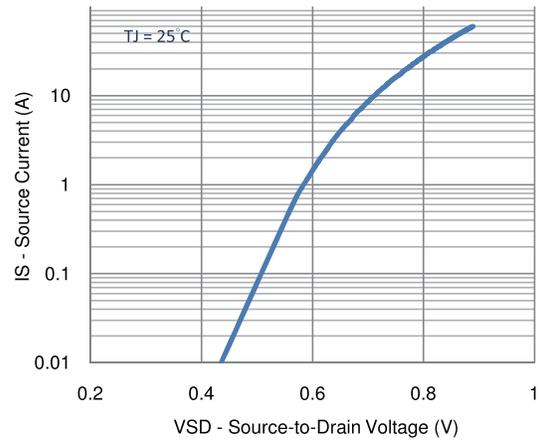
1. On-Resistance vs. Drain Current



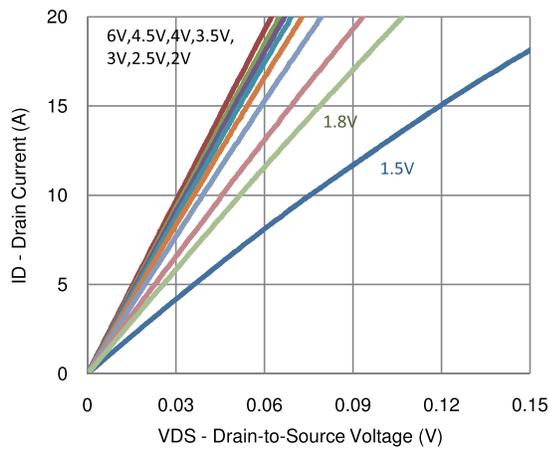
2. Transfer Characteristics



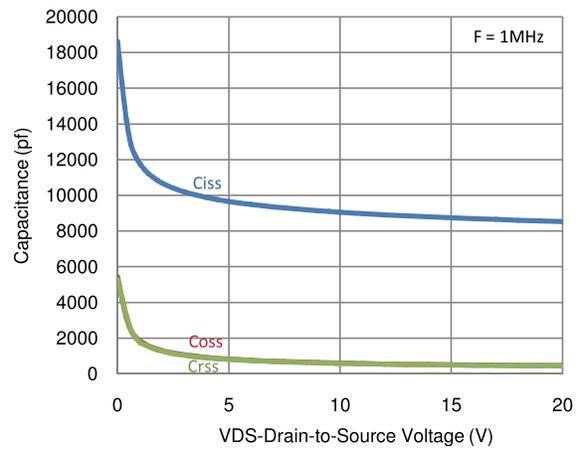
3. On-Resistance vs. Gate-to-Source Voltage



4. Drain-to-Source Forward Voltage

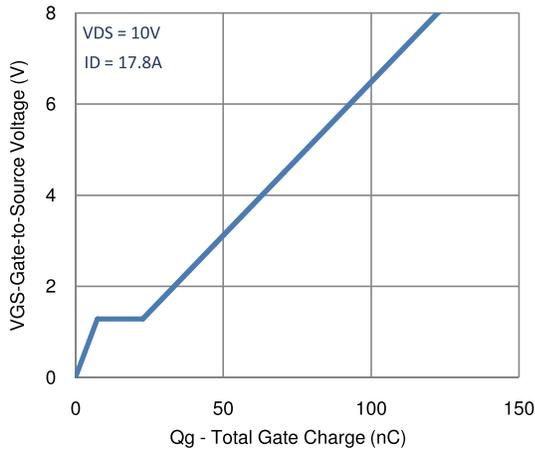


5. Output Characteristics

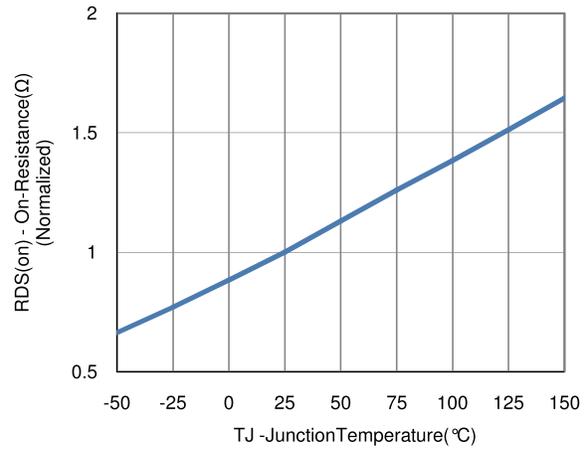


6. Capacitance

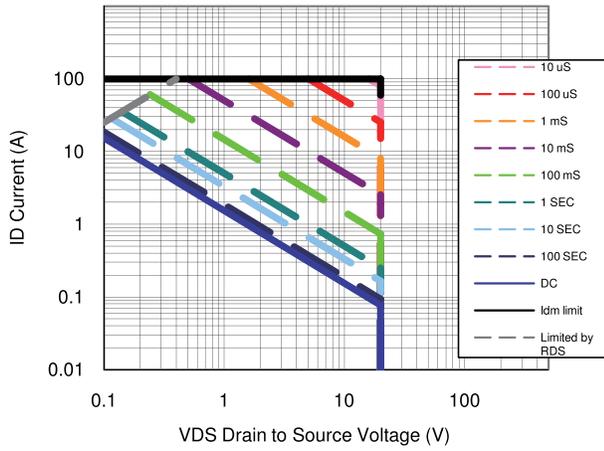
## Typical Electrical Characteristics



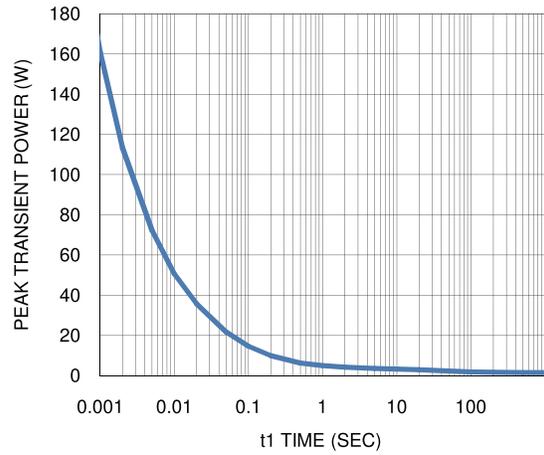
7. Gate Charge



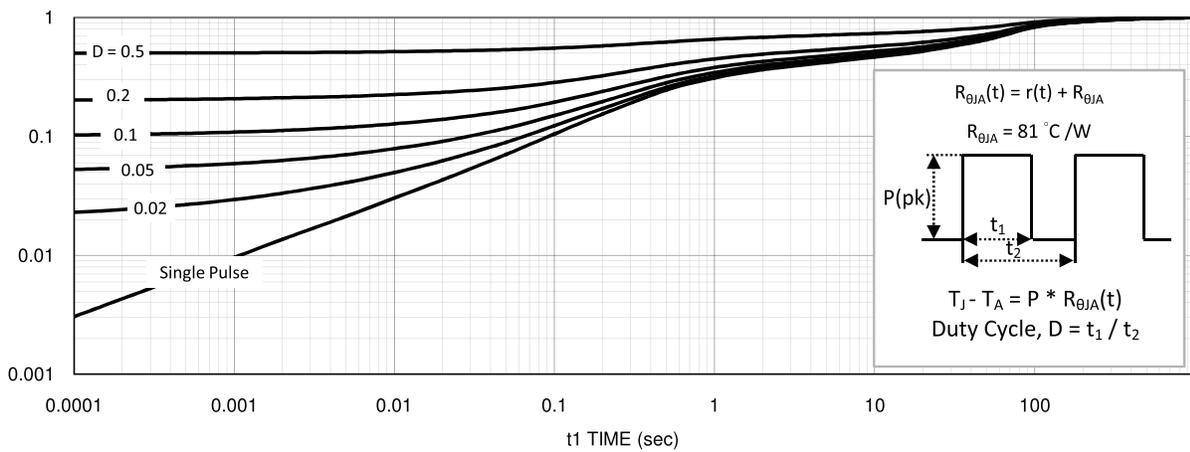
8. Normalized On-Resistance Vs Junction Temperature



9. Safe Operating Area

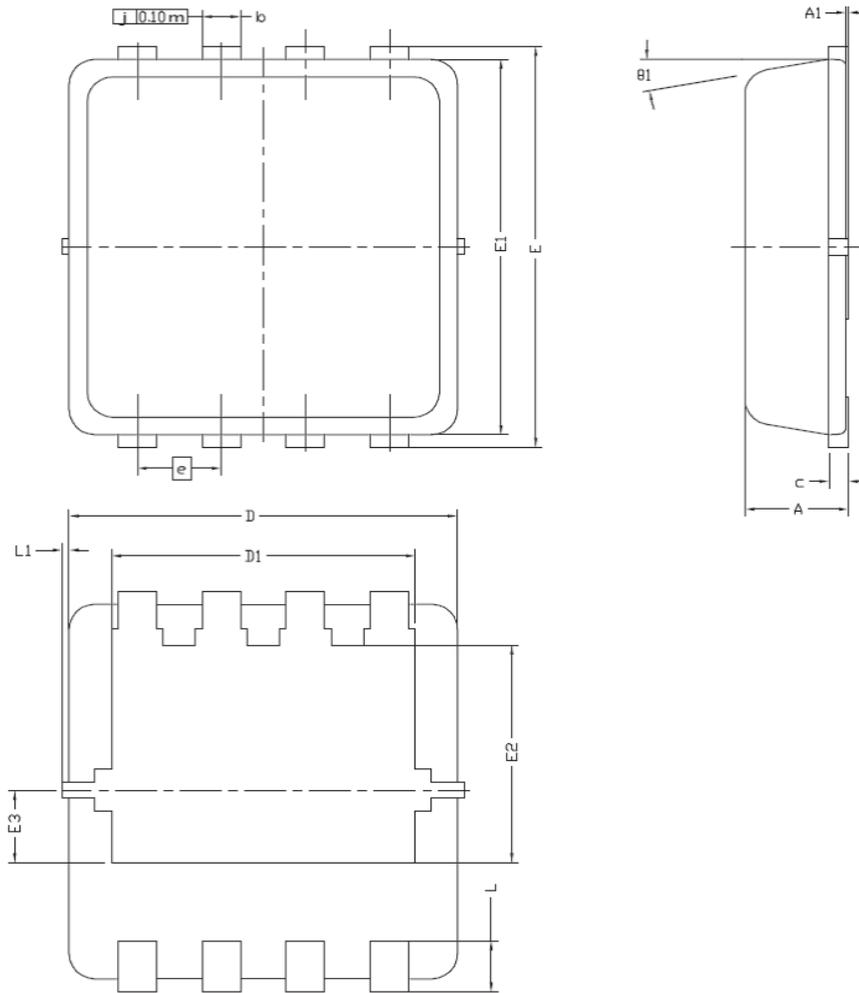


10. Single Pulse Maximum Power Dissipation



11. Normalized Thermal Transient Junction to Ambient

## Package Information



DIM.	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0,700	0,80	0,900	0,0276	0,0315	0,0354
A1	0,00	---	0,05	0,000	---	0,002
b	0,24	0,30	0,35	0,009	0,012	0,014
c	0,10	0,152	0,25	0,004	0,006	0,010
D	3,00 BSC			0,118 BSC		
D1	2,35 BSC			0,093 BSC		
E	3,20 BSC			0,126 BSC		
E1	3,00 BSC			0,118 BSC		
E2	1,75 BSC			0,069 BSC		
E3	0,575 BSC			0,023 BSC		
e	0,65 BSC			0,026 BSC		
L	0,30	0,40	0,50	0,0118	0,0157	0,0197
L1	0	---	0,100	0	---	0,004
$\theta 1$	0°	10°	12°	0°	10°	12°